

# ABSTRACT

A porous film-forming composition comprising (A) a  
5 curable silicone resin having a Mn of at least 100, (B) a  
micelle-forming surfactant, and (C) a compound which  
generates an acid upon pyrolysis remains stable during  
storage. The composition is coated and heat treated to form  
a porous film which has flatness, uniformity, a low  
10 dielectric constant and a high mechanical strength so that it  
is best suited as an interlayer dielectric film in the  
fabrication of semiconductor devices.